# Abstracts

## 77-GHz-band surface mountable ceramic package

*K. Kitazawa, S. Koriyama, H. Minamiue and M. Fujii. "77-GHz-band surface mountable ceramic package." 2000 Transactions on Microwave Theory and Techniques 48.9 (Sep. 2000 [T-MTT] (Mini-Special Issue on Research Reported at the 8th Topical Meeting on Electrical Performance of Electronic Packaging (EPEP) 1999)): 1488-1491.*

The authors have developed a surface mount-type ceramic package for 77-GHz millimeter-wave application. The package has a new terminal structure for surface mount and a feedthrough of electromagnetic coupling. The authors have adopted a coplanar structure for the surface mount terminal. The structure for the electromagnetic coupling consists of microstrip line/slot/microstrip line (MSL/SLOT/MSL). Total transmission loss between the signal line on board and the RF input-output terminal inside the package was 1.0 dB at 77 GHz Standard deviation of the insertion loss was 0.08 dB (n = 57) The authors have confirmed that the surface mountable package shows high transmission characteristics as well as high reliability.

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